

	Type	L #	Hits	Search Text	DBs	Time Stamp
1	IS&R	L1	490	(438/613).CCLS.	USPAT	2002/11/19 17:27

	Type	L #	Hits	Search Text	DBs	Time Stamp
1	IS&R	L1	554	(438/612).CCLS.	USPAT	2002/11/20 08:58
2	IS&R	L3	366	(438/614).CCLS.	USPAT	2002/11/20 09:16
3	BRS	L5	285	(planari\$3) adj10 (bump or bumps or solder or solders)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2002/11/20 09:40
4	BRS	L9	8553	(reform\$3 or reflow\$3) adj10 ((conductive adj3 bump) or solder or solders)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2002/11/20 09:43
5	BRS	L10	6	(reform\$3) adj10 (conductive adj3 bump) same (preplanariz\$3)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2002/11/20 09:42
6	BRS	L11	19	(reform\$3 or reflow\$3) adj10 ((conductive adj3 bump) or solder or solders) same (preplanariz\$3 or planariz\$3)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2002/11/20 09:49

	Type	L #	Hits	Search Text	DBs	Time Stamp
7	BRS	L12	7	(planarize or planarized or planarizing) adj10 (conductive adj3 bump)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2002/11/20 09:50

L1 planar \$6 or preplanar \$6 or
CMP or flat \$6

L2 bump or ball or BGA.

L3 L1 near ⁸4 L2

L4 reflow \$7 or reconstituted \$4 or reform \$4 or
redump \$7

L5 L4 near ⁹4 L2

L6 L3 ~~near~~ L5
and

	Type	L #	Hits	Search Text	DBs	Time Stamp
1	BRS	L1	92	(reform or reforming or reformed) adj10 (solder or solders or bump or bumps)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2002/11/20 15:27